



Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 2011 Sockets



IC Socket Type: **LGA 2011**  
 Number of Positions: **2011**  
 Contact Mating Area Plating Material Thickness: [ 30 µin ]  
 Centerline (Pitch): 1.02 mm [ .04 in ]  
 Termination Method to Printed Circuit Board: **Surface Mount - Solder Ball**

## Features

### Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Number of Positions	2011
Grid Spacing	1.016 x .8814 mm [.040 x .0347 in]

### Body Features

Frame Style	Square
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### Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 2011
	30 µin
Contact Current Rating (Max)	.5 A

### Termination Features

Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
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### Mechanical Attachment

Connector Mounting Type	Board Mount
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### Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	1.02 mm[.04 in]

### Usage Conditions

Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Tray Color	Black
Packaging Method	Tray

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Customers Also Bought



## Documents

### Product Drawings

[SOCKET ASSY LGA2011-3 0.76um Au](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2201838-2\\_C.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2201838-2\\_C.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2201838-2\\_C.3d\\_stp.zip](#)

English

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### Product Specifications



## Application Specification

English